## 200MHz Rail-to-Rail Amplifiers

The EL8200, EL8201, and EL8401 represent rail-to-rail amplifiers with a -3 dB bandwidth of 200 MHz and slew rate of $200 \mathrm{~V} / \mu \mathrm{s}$. Running off a very low supply current of 2 mA per channel, the EL8200, EL8201, and EL8401 also feature inputs that go to 0.15 V below the $\mathrm{V}_{\mathrm{S}^{-}}$rail. The EL8200 and EL8201 are dual channel amplifiers. The EL8401 is a quad channel amplifier.

The EL8200 includes a fast-acting disable/power-down circuit. With a 25 ns disable and a 200 ns enable, the EL8200 is ideal for multiplexing applications.

The EL8200, EL8201, and EL8401 are designed for a number of general purpose video, communication, instrumentation, and industrial applications. The EL8200 is available in a 10 Ld MSOP package, the EL8201 in an 8 Ld SO and 8 Ld MSOP package, and the EL8401 in a 14 Ld SO and 16 Ld QSOP packages. All are specified for operation over the $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ temperature range.

## Features

- $200 \mathrm{MHz}-3 \mathrm{~dB}$ bandwidth
- 200V/ $\mu$ s slew rate
- Low supply current $=2 \mathrm{~mA}$ per channel
- Supplies from 3 V to 5.5 V
- Rail-to-rail output
- Input to 0.15 V below $\mathrm{V}^{-}$-
- Fast 25 ns disable (EL8200 only)
- Low cost
- Pb-free available (RoHS compliant)


## Applications

- Video amplifiers
- Portable/hand-held products
- Communications devices


## Pinouts



## Ordering Information

| PART NUMBER | PART MARKING | PACKAGE | PKG. DWG. \# |
| :---: | :---: | :---: | :---: |
| EL8200IY | j | 10 Ld MSOP | MDP0043 |
| EL8200IY-T7* | j | 10 Ld MSOP | MDP0043 |
| EL8200IY-T13* | j | 10 Ld MSOP | MDP0043 |
| EL8200IYZ (See Note) | BAMAA | 10 Ld MSOP (Pb-free) | MDP0043 |
| EL8200IYZ-T7* (See Note) | BAMAA | 10 Ld MSOP (Pb-free) | MDP0043 |
| EL8200IYZ-T13* (See Note) | BAMAA | 10 Ld MSOP (Pb-free) | MDP0043 |
| EL8201IS | 8201IS | 8 Ld SO | MDP0027 |
| EL8201IS-T7* | 82011S | 8 Ld SO | MDP0027 |
| EL8201IS-T13* | 8201IS | 8 Ld SO | MDP0027 |
| EL8201ISZ (See Note) | 8201ISZ | 8 Ld SO (Pb-free) | MDP0027 |
| EL8201ISZ-T7* (See Note) | 8201ISZ | 8 Ld SO (Pb-free) | MDP0027 |
| EL8201ISZ-T13* (See Note) | 8201ISZ | 8 Ld SO (Pb-free) | MDP0027 |
| Coming Soon EL8201IYZ (See Note) |  | 8 Ld MSOP (Pb-free) | MDP0043 |
| Coming Soon <br> EL8201IYZ-T7* (See Note) |  | 8 Ld MSOP (Pb-free) | MDP0043 |
| Coming Soon <br> EL8201IYZ-T13* (See Note) |  | 8 Ld MSOP (Pb-free) | MDP0043 |
| EL8401IS | 84011S | 14 Ld SO | MDP0027 |
| EL8401IS-T7* | 8401IS | 14 Ld SO | MDP0027 |
| EL8401IS-T13* | 8401IS | 14 Ld SO | MDP0027 |
| EL8401ISZ (See Note) | 8401ISZ | 14 Ld SO (Pb-free) | MDP0027 |
| EL8401ISZ-T7* (See Note) | 8401ISZ | 14 Ld SO (Pb-free) | MDP0027 |
| EL8401ISZ-T13* (See Note) | 8401ISZ | 14 Ld SO (Pb-free) | MDP0027 |
| EL8401IU | 8401IU | 16 Ld QSOP | MDP0040 |
| EL8401IU-T7* | 8401 U | 16 Ld QSOP | MDP0040 |
| EL8401IU-T13* | 8401 IU | 16 Ld QSOP | MDP0040 |
| EL8401IUZ (See Note) | 8401IUZ | 16 Ld QSOP (Pb-free) | MDP0040 |
| EL8401IUZ-T7* (See Note) | 8401IUZ | 16 Ld QSOP (Pb-free) | MDP0040 |
| EL8401IUZ-T13* (See Note) | 8401IUZ | 16 Ld QSOP (Pb-free) | MDP0040 |

*Please refer to TB347 for details on reel specifications.
NOTE: These Intersil Pb-free plastic packaged products employ special Pb-free material sets; molding compounds/die attach materials and 100\% matte tin plate PLUS ANNEAL - e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

```
Absolute Maximum Ratings \(\left(\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}\right)\)
```

Supply Voltage from $\mathrm{V}_{\mathrm{S}^{+}}$to $\mathrm{V}_{\mathrm{S}^{-}} \ldots \ldots$. . . . . . . . . . . . . . . . . . . 5.5 V Input Voltage . . . . . . . . . . . . . . . . . . . . . . . . . $\mathrm{V}_{\mathrm{S}^{+}}+0.3 \mathrm{~V}$ to $\mathrm{V}_{\mathrm{S}^{-}}-0.3 \mathrm{~V}$ Differential Input Voltage . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . 2 V Continuous Output Current

40 mA

Power Dissipation
. See Curves
Storage Temperature
$-65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$
Ambient Operating Temperature . . . . . . . . . . . . . . . . $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$
Operating Junction Temperature
$+125^{\circ} \mathrm{C}$

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

IMPORTANT NOTE: All parameters having Min/Max specifications are guaranteed. Typ values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore: $T_{J}=T_{C}=T_{A}$

Electrical Specifications $\quad \mathrm{V}_{\mathrm{S}^{+}}=5 \mathrm{~V}, \mathrm{~V}_{\mathrm{S}^{-}}=\mathrm{GND}, \mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{CM}}=2.5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}$ to $2.5 \mathrm{~V}, \mathrm{~A}_{\mathrm{V}}=1$, Unless Otherwise Specified

| PARAMETER | DESCRIPTION | CONDITIONS | MIN (Note 1) | TYP | MAX <br> (Note 1) | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| INPUT CHARACTERISTICS |  |  |  |  |  |  |
| $\mathrm{V}_{\text {OS }}$ | Offset Voltage |  | -6 | -0.8 | +6 | mV |
| TCV ${ }_{\text {OS }}$ | Offset Voltage Temperature Coefficient | Measured from $\mathrm{T}_{\text {MIN }}$ to $\mathrm{T}_{\text {MAX }}$ |  | 3 |  | $\mu \mathrm{V} /{ }^{\circ} \mathrm{C}$ |
| IB | Input Bias Current | $\mathrm{V}_{\mathrm{IN}}=0 \mathrm{~V}$ | -2.5 | -1.6 |  | $\mu \mathrm{A}$ |
| los | Input Offset Current | $\mathrm{V}_{\mathrm{IN}}=0 \mathrm{~V}$ |  | 0.2 | 0.55 | $\mu \mathrm{A}$ |
| $\mathrm{TCl}_{\mathrm{OS}}$ | Input Bias Current Temperature Coefficient | Measured from $\mathrm{T}_{\text {MIN }}$ to $\mathrm{T}_{\text {MAX }}$ |  | 2 |  | $\mathrm{nA} /{ }^{\circ} \mathrm{C}$ |
| CMRR | Common Mode Rejection Ratio | $\mathrm{V}_{\mathrm{CM}}=-0.15 \mathrm{~V}$ to +3.5V (EL8200,EL8201) | 70 | 90 |  | dB |
|  |  | $\mathrm{V}_{\mathrm{CM}}=-0.15 \mathrm{~V}$ to $+3.5 \mathrm{~V}(\mathrm{EL} 8401)$ | 65 | 90 |  | dB |
| CMIR | Common Mode Input Range |  | $\mathrm{V}_{\text {S }}-0.15$ |  | $\mathrm{V}_{\mathrm{S}^{+}-1.5}$ | V |
| $\mathrm{R}_{\text {IN }}$ | Input Resistance | Common Mode |  | 16 |  | $\mathrm{M} \Omega$ |
| $\mathrm{C}_{\text {IN }}$ | Input Capacitance |  |  | 0.5 |  | pF |
| AVOL | Open Loop Gain | $\mathrm{V}_{\text {OUT }}=+1.5 \mathrm{~V}$ to $+3.5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=1 \mathrm{k} \Omega$ to GND | 75 | 90 |  | dB |
|  |  | $\mathrm{V}_{\text {OUT }}=+1.5 \mathrm{~V}$ to $+3.5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=150 \Omega$ to GND |  | 80 |  | dB |
| OUTPUT CHARACTERISTICS |  |  |  |  |  |  |
| ROUT | Output Resistance | $A_{V}=+1$ |  | 30 |  | $\mathrm{m} \Omega$ |
| $\mathrm{V}_{\text {OP }}$ | Positive Output Voltage Swing | $R_{L}=1 \mathrm{k} \Omega$ | 4.85 | 4.9 |  | V |
|  |  | $R_{L}=150 \Omega$ | 4.6 | 4.7 |  | V |
| $\mathrm{V}_{\mathrm{ON}}$ | Negative Output Voltage Swing | $R_{L}=150 \Omega$ |  | 100 | 150 | mV |
|  |  | $R_{L}=1 \mathrm{k} \Omega$ |  | 35 | 50 | mV |
| lout | Linear Output Current |  |  | 65 |  | mA |
| ISC (source) | Short Circuit Current | $\mathrm{R}_{\mathrm{L}}=10 \Omega$ | 60 | 70 |  | mA |
| ISC (sink) | Short Circuit Current | $\mathrm{R}_{\mathrm{L}}=10 \Omega$ | 100 | 130 |  | mA |
| POWER SUPPLY |  |  |  |  |  |  |
| PSRR | Power Supply Rejection Ratio | $\mathrm{V}_{\mathrm{S}^{+}}=4.5 \mathrm{~V}$ to 5.5 V | 70 | 100 |  | dB |
| IS-ON | Supply Current |  |  | 2 | 2.4 | mA |
| IS-OFF | Supply Current - Disabled per Amplifier | EL8200 only |  | 40 | 90 | $\mu \mathrm{A}$ |
| ENABLE (EL8200 ONLY) |  |  |  |  |  |  |
| $\mathrm{t}_{\mathrm{EN}}$ | Enable Time |  |  | 200 |  | ns |
| $\mathrm{t}_{\mathrm{DS}}$ | Disable Time |  |  | 25 |  | ns |
| $\mathrm{V}_{\text {IH-ENB }}$ | $\overline{\text { ENABLE }}$ Pin Voltage for Power-up |  |  | 0.8 |  | V |

Electrical Specifications $\quad \mathrm{V}_{\mathrm{S}^{+}}=5 \mathrm{~V}, \mathrm{~V}_{\mathrm{S}^{-}}=\mathrm{GND}, \mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{CM}}=2.5 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}$ to $2.5 \mathrm{~V}, \mathrm{~A}_{\mathrm{V}}=1$, Unless Otherwise Specified (Continued)

| PARAMETER | DESCRIPTION | CONDITIONS | $\begin{gathered} \text { MIN } \\ \text { (Note 1) } \end{gathered}$ | TYP | $\begin{gathered} \text { MAX } \\ \text { (Note 1) } \end{gathered}$ | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {IL-ENB }}$ | ENABLE Pin Voltage for Shut-down |  |  | 2 |  | V |
| IIH-ENB | ENABLE Pin Input Current High |  |  | 8.6 |  | $\mu \mathrm{A}$ |
| ILL-ENB | ENABLE Pin Input for Current Low |  |  | 0.01 |  | $\mu \mathrm{A}$ |

AC PERFORMANCE

| BW | -3dB Bandwidth | $A_{V}=+1, R_{F}=0 \Omega, C_{L}=1.5 p F$ |  | 200 | MHz |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | $A_{V}=-1, R_{F}=1 \mathrm{k} \Omega, C_{L}=1.5 \mathrm{pF}$ |  | 90 | MHz |
|  |  | $A_{V}=+2, R_{F}=1 \mathrm{k} \Omega, C_{L}=1.5 \mathrm{pF}$ |  | 90 | MHz |
|  |  | $A_{V}=+10, R_{F}=1 \mathrm{k} \Omega, C_{L}=1.5 \mathrm{pF}$ |  | 10 | MHz |
| BW | $\pm 0.1 \mathrm{~dB}$ Bandwidth | $A_{V}=+1, R_{F}=0 \Omega, C_{L}=1.5 p F$ |  | 20 | MHz |
| Peak | Peaking | $A_{V}=+1, R_{F}=1 \mathrm{k} \Omega, C_{L}=1.5 \mathrm{pF}$ |  | 1 | dB |
| GBWP | Gain Bandwidth Product |  |  | 100 | MHz |
| PM | Phase Margin | $R_{L}=1 \mathrm{k} \Omega, C_{L}=1.5 \mathrm{pF}$ |  | 55 | - |
| SR | Slew Rate | $A_{V}=2, R_{L}=100 \Omega, V_{\text {OUT }}=0.5 \mathrm{~V}$ to 4.5 V | 160 | 200 | V/ $/ \mathrm{s}$ |
| $\mathrm{t}_{\mathrm{R}}$ | Rise Time | $2.5 \mathrm{~V}_{\text {STEP, }}$, $20 \%-80 \%$ |  | 8 | ns |
| $\mathrm{t}_{\mathrm{F}}$ | Fall Time | $2.5 \mathrm{~V}_{\text {STEP }}, 20 \%-80 \%$ |  | 7 | ns |
| OS | Overshoot | 200 mV step |  | 10 | \% |
| tpd | Propagation Delay | 200 mV step |  | 2 | ns |
| ts | 0.1\% Settling Time | 200mV step |  | 20 | ns |
| dG | Differential Gain | $A_{V}=+2, R_{F}=1 \mathrm{k} \Omega, \mathrm{R}_{\mathrm{L}}=150 \Omega$ |  | 0.035 | \% |
| dP | Differential Phase | $A_{V}=+2, R_{F}=1 \mathrm{k} \Omega, \mathrm{R}_{\mathrm{L}}=150 \Omega$ |  | 0.05 | - |
| $\mathrm{e}_{\mathrm{N}}$ | Input Noise Voltage | $\mathrm{f}=10 \mathrm{kHz}$ |  | 10 | $\mathrm{nV} / \sqrt{\mathrm{Hz}}$ |
| $\mathrm{i}^{+}+$ | Positive Input Noise Current | $\mathrm{f}=10 \mathrm{kHz}$ |  | 1 | $\mathrm{pA} / \sqrt{ } \mathrm{Hz}$ |
| $\mathrm{i}_{\mathrm{N}}{ }^{-}$ | Negative Input Noise Current | $\mathrm{f}=10 \mathrm{kHz}$ |  | 0.8 | $\mathrm{pA} / \sqrt{ } \mathrm{Hz}$ |
| $\mathrm{e}_{S}$ | Channel Separation | $\mathrm{f}=100 \mathrm{kHz}$ |  | 95 | dB |

NOTE:

1. Parts are $100 \%$ tested at $+25^{\circ} \mathrm{C}$. Over-temperature limi ts established by characterization and are not production tested.

## Pin Descriptions

| $\begin{aligned} & \text { EL8200 } \\ & \text { (10 Ld SO) } \end{aligned}$ | $\begin{gathered} \text { EL8201 } \\ \text { (8 Ld SO, } 8 \text { Ld MSOP) } \end{gathered}$ | $\begin{aligned} & \text { EL8401 } \\ & \text { (14 Ld SO) } \end{aligned}$ | $\begin{gathered} \text { EL8401 } \\ \text { (16 Ld QSOP) } \end{gathered}$ | NAME | FUNCTION |
| :---: | :---: | :---: | :---: | :---: | :---: |
| 1,5 | 3, 5 | $3,5,10,12$ | $3,5,12,14$ | $\mathrm{IN}+$ | Non-inverting input for each channel |
| 2, 4 |  |  |  | $\overline{\mathrm{CE}}$ | Enable and disable input for each channel |
| 3 | 4 | 11 | 13 | VS- | Negative power supply |
| 6,10 | 2, 6 | 2, 6, 9, 13 | 2, 6, 11, 15 | IN - | Inverting input for each channel |
| 7, 9 | 1, 7 | 1, 7, 8, 14 | 1, 7, 10, 16 | OUT | Amplifier output for each channel |
| 8 | 8 | 4 | 4 | VS+ | Positive power supply |

## Typical Performance Curves



FIGURE 1. FREQUENCY RESPONSE FOR VARIOUS OUTPUT VOLTAGE LEVELS


FIGURE 3. SMALL SIGNAL FREQUENCY RESPONSE FOR VARIOUS NON-INVERTING GAINS


FIGURE 5. SMALL SIGNAL FREQUENCY RESPONSE FOR VARIOUS $C_{L}$


FIGURE 2. SMALL SIGNAL FREQUENCY RESPONSE FOR VARIOUS RLOAD


FIGURE 4. SMALL SIGNAL FREQUENCY RESPONSE FOR VARIOUS INVERTING GAINS


FIGURE 6. SMALL SIGNAL FREQUENCY RESPONSE FOR VARIOUS $C_{L}$

## Typical Performance Curves (Continued)



FIGURE 7. SMALL SIGNAL FREQUENCY RESPONSE FOR VARIOUS $^{R_{F}}$ AND $\mathbf{R}_{G}$


FIGURE 9. COMMON-MODE REJECTION RATIO vs FREQUENCY


FIGURE 11. OUTPUT IMPEDANCE vs FREQUENCY


FIGURE 8. OPEN LOOP GAIN AND PHASE vs FREQUENCY


FIGURE 10. SMALL SIGNAL BANDWIDTH vs SUPPLY VOLTAGE


FIGURE 12. SMALL SIGNAL PEAKING vs SUPPLY VOLTAGE

## Typical Performance Curves (Continued)



FIGURE 13. POWER SUPPLY REJECTION RATIO vs FREQUENCY


FIGURE 15. DISABLED OUTPUT ISOLATION FREQUENCY RESPONSE


FIGURE 17. HARMONIC DISTORTION vs LOAD RESISTANCE


FIGURE 14. HARMONIC DISTORTION vs OUTPUT VOLTAGE


FIGURE 16. HARMONIC DISTORTION vs FREQUENCY


FIGURE 18. VOLTAGE AND CURRENT NOISE vs FREQUENCY

Typical Performance Curves (Continued)


FIGURE 19. CHANNEL SEPARATION vs FREQUENCY (EL8200 AND EL8201)


10ns/DIV

FIGURE 21. LARGE SIGNAL TRANSIENT RESPONSE


FIGURE 23. SMALL SIGNAL TRANSIENT RESPONSE


FIGURE 20. CHANNEL SEPARATION vs FREQUENCY (EL8401)
$\mathrm{V}_{\mathrm{S}}=5 \mathrm{~V}, \mathrm{~A}_{\mathrm{V}}=5, \mathrm{R}_{\mathrm{L}}=1 \mathrm{k} \Omega$ to 2.5 V


FIGURE 22. OUTPUT SWING


FIGURE 24. OUTPUT SWING

## Typical Performance Curves (Continued)



CH1, CH2, 0.5V/DIV, M=20ns
FIGURE 25. DISABLED RESPONSE (EL8200)


FIGURE 27. PACKAGE POWER DISSIPATION vs AMBIENT TEMPERATURE


FIGURE 26. ENABLED RESPONSE (EL8200)


FIGURE 28. PACKAGE POWER DISSIPATION vs AMBIENT TEMPERATURE

## Simplified Schematic Diagram



## Description of Operation and Application Information

## Product Description

The EL8200, EL8201 and EL8401 are wide bandwidth, single supply, low power and rail-to-rail output voltage feedback operational amplifiers. The amplifiers are internally compensated for closed loop gain of +1 of greater. Connected in voltage follower mode and driving a $1 \mathrm{k} \Omega$ load, they have a -3 dB bandwidth of 200 MHz . Driving a $150 \Omega$ load, the bandwidth is about 130 MHz while maintaining a 200 V /us slew rate. The EL8200 is available with a power down pin to reduce power to $30 \mu \mathrm{~A}$ typically while the amplifier is disabled.

## Input, Output and Supply Voltage Range

The EL8200, EL8201 and EL8401 have been designed to operate with a single supply voltage from 3 V to 5.0 V . Split supplies can also be used as long as their total voltage is within 3 V to 5.0 V . The amplifiers have an input common mode voltage range from 0.15 V below the negative supply ( $\mathrm{V}_{\mathrm{S}^{-}}$pin) to within 1.5 V of the positive supply $\left(\mathrm{V}_{\mathrm{S}^{+}}\right.$pin). If the input signal is outside the above specified range, it will cause the output signal to be distorted.

The output of the EL8200, EL8201 and EL8401 can swing rail to rail. As the load resistance becomes lower, the ability to drive close to each rail is reduced. For the load resistor $1 \mathrm{k} \Omega$, the output swing is about 4.9 V at a 5 V supply. For the load resistor $150 \Omega$, the output swing is about 4.6 V .

## Choice of Feedback Resistor and Gain Bandwidth Product

For applications that require a gain of +1 , no feedback resistor is required. Just short the output pin to the inverting input pin. For gains greater than +1 , the feedback resistor forms a pole with the parasitic capacitance at the inverting input. As this pole becomes smaller, the amplifier's phase margin is reduced. This causes ringing in the time domain and peaking in the frequency domain. Therefore, $R_{F}$ has some maximum value that should not be exceeded for optimum performance. If a large value of $R_{F}$ must be used, a small capacitor in the few Pico farad range in parallel with $R_{F}$ can help to reduce the ringing and peaking at the expense of reducing the bandwidth.

As far as the output stage of the amplifier is concerned, the output stage is also a gain stage with the load. $R_{F}$ and $R_{G}$ appear in parallel with $R_{L}$ for gains other than +1 . As this combination gets smaller, the bandwidth falls off.
Consequently, $R_{F}$ also has a minimum value that should not be exceeded for optimum performance. For gain of $+1, R_{F}=0$ is optimum. For the gains other than +1 , optimum response is obtained with $\mathrm{R}_{\mathrm{F}}$ between $300 \Omega$ to $1 \mathrm{k} \Omega$.

The EL8200, EL8201 and EL8401 have a gain bandwidth product of 100 MHz . For gains $\geq 5$, its bandwidth can be predicted by the following equation:

Gain $\times$ BW $=100 \mathrm{MHz}$

## Video Performance

For good video performance, an amplifier is required to maintain the same output impedance and the same frequency response as DC levels are changed at the output. This is especially difficult when driving a standard video load of $150 \Omega$, because the change in output current with DC level. Special circuitry has been incorporated in the EL8200, EL8201 and EL8401 to reduce the variation of the output impedance with the current output. This results in dG and dP specifications of $0.03 \%$ and $0.05^{\circ}$, while driving $150 \Omega$ at a gain of 2 . Driving high impedance loads would give a similar or better dG and dP performance.

## Driving Capacitive Loads and Cables

The EL8200, EL8201 and EL8401 can drive 10pF loads in parallel with $1 \mathrm{k} \Omega$ with less than 5 dB of peaking at gain of +1 . If less peaking is desired in applications, a small series resistor (usually between $5 \Omega$ to $50 \Omega$ ) can be placed in series with the output to eliminate most peaking. However, this will reduce the gain slightly. If the gain setting is greater than 1 , the gain resistor $R_{G}$ can then be chosen to make up for any gain loss which may be created by the additional series resistor at the output.

When used as a cable driver, double termination is always recommended for reflection-free performance. For those applications, a back-termination series resistor at the amplifier's output will isolate the amplifier from the cable and allow extensive capacitive drive. However, other applications may have high capacitive loads without a back-termination resistor. Again, a small series resistor at the output can help to reduce peaking.

## Disable/Power-Down

The EL8200 can be disabled and placed its output in a high impedance state. The turn off time for each channel is about 25 ns and the turn on time is about 200ns. When disabled, the amplifier's supply current is reduced to $30 \mu \mathrm{~A}$ typically, thereby effectively eliminating the power consumption. The amplifier's power down can be controlled by standard TTL or CMOS signal levels at the $\overline{E N A B L E}$ pin. The applied logic signal is relative to $V_{S^{-}}$pin. Letting the $\overline{\text { ENABLE }}$ pin float or applying a signal that is less than 0.8 V above $\mathrm{V}_{\mathrm{S}}$ - will enable the amplifier. The amplifier will be disabled when the signal at $\overline{\text { ENABLE }}$ pin is 2 V above $\mathrm{V}_{\mathrm{S}^{-}}$.

## Output Drive Capability

The EL8200, EL8201 and EL8401 do not have internal short circuit protection circuitry. They have a typical short circuit current of 70 mA sourcing and 140 mA sinking for the output is connected to half way between the rails with a $10 \Omega$ resistor. If the output is shorted indefinitely, the power
dissipation could easily increase such that the part will be destroyed. Maximum reliability is maintained if the output current never exceeds $\pm 40 \mathrm{~mA}$. This limit is set by the design of the internal metal interconnections.

## Power Dissipation

With the high output drive capability of the EL8200, EL8201 and EL8401, it is possible to exceed the $125^{\circ} \mathrm{C}$ absolute maximum junction temperature under certain load current conditions. Therefore, it is important to calculate the maximum junction temperature for the application to determine if the load conditions or package types need to be modified for the amplifier to remain in the safe operating area.

The maximum power dissipation allowed in a package is determined according to:
$P D_{\text {MAX }}=\frac{T_{J M A X}-T_{\text {AMAX }}}{\theta_{J A}}$
Where:
TJMAX = Maximum junction temperature
$\mathrm{T}_{\text {AMAX }}=$ Maximum ambient temperature
$\theta_{\mathrm{JA}}=$ Thermal resistance of the package
The maximum power dissipation actually produced by an IC is the total quiescent supply current times the total power supply voltage, plus the power in the IC due to the load, or:

For sourcing:
$P D_{\text {MAX }}=V_{S} \times I_{\text {SMAX }}+\Sigma\left(V_{S}-V_{\text {OUTi }}\right) \times \frac{V_{\text {OUTi }}}{R_{\text {Li }}}$
For sinking:
$\mathrm{PD}_{\text {MAX }}=\mathrm{V}_{\mathrm{S}} \times \mathrm{I}_{\text {SMAX }}+\Sigma\left(\mathrm{V}_{\text {OUTi }}-\mathrm{V}_{\mathrm{S}^{-}}\right) \times \mathrm{I}_{\text {LOADi }}$

Where:

$$
\begin{aligned}
& \mathrm{V}_{\mathrm{S}}=\text { Total supply voltage } \\
& \mathrm{I}_{\text {SMAX }}=\text { Maximum quiescent supply current } \\
& \mathrm{V}_{\text {OUTi }}=\text { Maximum output voltage of the application for } \\
& \text { each channel } \\
& \mathrm{R}_{\text {LOADi }} \text { = Load resistance tied to ground for each channel } \\
& \text { LLOADi } \text { = Load current for each channel }
\end{aligned}
$$

By setting the two $P D_{\text {MAX }}$ equations equal to each other, we can solve the output current and R LOADi to avoid the device overheat.

## Power Supply Bypassing and Printed Circuit Board Layout

As with any high frequency device, a good printed circuit board layout is necessary for optimum performance. Lead lengths should be as sort as possible. The power supply pin must be well bypassed to reduce the risk of oscillation. For
normal single supply operation, where the $\mathrm{V}_{\mathrm{S}^{-}}$pin is connected to the ground plane, a single $4.7 \mu \mathrm{~F}$ tantalum capacitor in parallel with a $0.1 \mu \mathrm{~F}$ ceramic capacitor from $\mathrm{V}_{\mathrm{S}^{+}}$ to GND will suffice. This same capacitor combination should be placed at each supply pin to ground if split supplies are to be used. In this case, the $\mathrm{V}_{\mathrm{S}^{-}}$pin becomes the negative supply rail.

For good AC performance, parasitic capacitance should be kept to a minimum. Use of wire wound resistors should be avoided because of their additional series inductance. Use of sockets should also be avoided if possible. Sockets add parasitic inductance and capacitance that can result in compromised performance. Minimizing parasitic capacitance at the amplifier's inverting input pin is very important. The feedback resistor should be placed very close to the inverting input pin. Strip line design techniques are recommended for the signal traces.

## Typical Applications <br> VIDEO SYNC PULSE REMOVER

Many CMOS analog to digital converters have a parasitic latch up problem when subjected to negative input voltage levels. Since the sync tip contains no useful video information and it is a negative going pulse, we can chop it off. Figure 29 shows a gain of 2 connections. Figure 30 shows the complete input video signal applied at the input, as well as the output signal with the negative going sync pulse removed.

## MULTIPLEXER

Besides the normal power down usage, the ENABLE pin of the EL8200 can be used for multiplexing applications.
Figure 31 shows two channels with the outputs tied together, driving a back terminated $75 \Omega$ video load. A $2 \mathrm{~V}_{\mathrm{P}-\mathrm{P}} 2 \mathrm{MHz}$ sine wave is applied to Amp A and a $1 \mathrm{~V}_{\mathrm{P}-\mathrm{p}} 2 \mathrm{MHz}$ sine wave is applied to Amp B. Figure 32 shows the ENABLE signal and the resulting output waveform at $\mathrm{V}_{\text {OUT }}$. Observe the break-before-make operation of the multiplexing. Amp A is on and $\mathrm{V}_{\mathbb{I N} 1}$ is passed through to the output when the ENABLE signal is low and turns off in about 25 ns when the $\overline{\text { ENABLE signal is high. About } 200 \mathrm{~ns} \text { later, Amp B turns on }}$ and $\mathrm{V}_{\mathrm{IN} 2}$ is passed through to the output. The break-beforemake operation ensures that more than one amplifier isn't trying to drive the bus at the same time.



FIGURE 30. VIDEO SIGNAL


FIGURE 31. TWO TO ONE MULTIPLEXER


FIGURE 32. ENABLE SIGNAL

## SINGLE SUPPLY VIDEO LINE DRIVER

The EL8200, EL8201 and EL8401 are wideband rail-to-rail output op amplifiers with large output current, excellent dG, dP , and low distortion that allow them to drive video signals in low supply applications. Figure 33 is the single supply non-inverting video line driver configuration and Figure 34 is the inverting video ling driver configuration. The signal is AC coupled by $C_{1}$. $R_{1}$ and $R_{2}$ are used to level shift the input and output to provide the largest output swing. $R_{F}$ and $R_{G}$
set the $A C$ gain. $C_{2}$ isolates the virtual ground potential. $R_{T}$ and $R_{3}$ are the termination resistors for the line. $C_{1}, C_{2}$ and $\mathrm{C}_{3}$ are selected big enough to minimize the droop of the luminance signal.


FIGURE 33. 5V SINGLE SUPPLY NON INVERTING VIDEO LINE DRIVER


FIGURE 34. 5V SINGLE SUPPLY INVERTING VIDEO LINE DRIVER


FIGURE 35. VIDEO LINE DRIVER FREQUENCY RESPONSE

## Small Outline Package Family (SO)



| (\$0.010 (1) | C | A | B |
| :--- | :--- | :--- | :--- |



## MDP0027

SMALL OUTLINE PACKAGE FAMILY (SO)

| SYMBOL | INCHES |  |  |  |  |  |  | TOLERANCE | NOTES |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | SO-8 | SO-14 | $\begin{gathered} \text { SO16 } \\ (0.150 ") \end{gathered}$ | $\begin{gathered} \text { SO16 (0.300") } \\ \text { (SOL-16) } \end{gathered}$ | $\begin{gathered} \text { SO20 } \\ \text { (SOL-20) } \end{gathered}$ | $\begin{gathered} \text { SO24 } \\ (\mathrm{SOL}-24) \end{gathered}$ | $\begin{gathered} \text { SO28 } \\ \text { (SOL-28) } \end{gathered}$ |  |  |
| A | 0.068 | 0.068 | 0.068 | 0.104 | 0.104 | 0.104 | 0.104 | MAX | - |
| A1 | 0.006 | 0.006 | 0.006 | 0.007 | 0.007 | 0.007 | 0.007 | $\pm 0.003$ | - |
| A2 | 0.057 | 0.057 | 0.057 | 0.092 | 0.092 | 0.092 | 0.092 | $\pm 0.002$ | - |
| b | 0.017 | 0.017 | 0.017 | 0.017 | 0.017 | 0.017 | 0.017 | $\pm 0.003$ | - |
| c | 0.009 | 0.009 | 0.009 | 0.011 | 0.011 | 0.011 | 0.011 | $\pm 0.001$ | - |
| D | 0.193 | 0.341 | 0.390 | 0.406 | 0.504 | 0.606 | 0.704 | $\pm 0.004$ | 1, 3 |
| E | 0.236 | 0.236 | 0.236 | 0.406 | 0.406 | 0.406 | 0.406 | $\pm 0.008$ | - |
| E1 | 0.154 | 0.154 | 0.154 | 0.295 | 0.295 | 0.295 | 0.295 | $\pm 0.004$ | 2, 3 |
| e | 0.050 | 0.050 | 0.050 | 0.050 | 0.050 | 0.050 | 0.050 | Basic | - |
| L | 0.025 | 0.025 | 0.025 | 0.030 | 0.030 | 0.030 | 0.030 | $\pm 0.009$ | - |
| L1 | 0.041 | 0.041 | 0.041 | 0.056 | 0.056 | 0.056 | 0.056 | Basic | - |
| h | 0.013 | 0.013 | 0.013 | 0.020 | 0.020 | 0.020 | 0.020 | Reference | - |
| N | 8 | 14 | 16 | 16 | 20 | 24 | 28 | Reference | - |

NOTES:
Rev. M 2/07

1. Plastic or metal protrusions of 0.006 " maximum per side are not included.
2. Plastic interlead protrusions of $0.010^{\prime \prime}$ maximum per side are not included.
3. Dimensions "D" and "E1" are measured at Datum Plane "H".
4. Dimensioning and tolerancing per ASME Y14.5M-1994

## Quarter Size Outline Plastic Packages Family (QSOP)



MDP0040
QUARTER SIZE OUTLINE PLASTIC PACKAGES FAMILY

| SYMBOL | INCHES |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | QSOP16 | QSOP24 | QSOP28 | TOLERANCE | NOTES |
| A | 0.068 | 0.068 | 0.068 | Max. | - |
| A1 | 0.006 | 0.006 | 0.006 | $\pm 0.002$ | - |
| A2 | 0.056 | 0.056 | 0.056 | $\pm 0.004$ | - |
| b | 0.010 | 0.010 | 0.010 | $\pm 0.002$ | - |
| c | 0.008 | 0.008 | 0.008 | $\pm 0.001$ | - |
| D | 0.193 | 0.341 | 0.390 | $\pm 0.004$ | 1,3 |
| E | 0.236 | 0.236 | 0.236 | $\pm 0.008$ | - |
| E1 | 0.154 | 0.154 | 0.154 | $\pm 0.004$ | 2,3 |
| e | 0.025 | 0.025 | 0.025 | Basic | - |
| L | 0.025 | 0.025 | 0.025 | $\pm 0.009$ | - |
| L1 | 0.041 | 0.041 | 0.041 | Basic | - |
| N | 16 | 24 | 28 | Reference | - |

Rev. F 2/07
NOTES:

1. Plastic or metal protrusions of 0.006 " maximum per side are not included.
2. Plastic interlead protrusions of 0.010 " maximum per side are not included.
3. Dimensions "D" and "E1" are measured at Datum Plane "H".
4. Dimensioning and tolerancing per ASME Y14.5M-1994.

## Mini SO Package Family (MSOP)



## MDP0043

MINI SO PACKAGE FAMILY

| SYMBOL | MILLIMETERS |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
|  | MSOP8 | MSOP10 | TOLERANCE |  |
| A | 1.10 | 1.10 | Max. | - |
| A1 | 0.10 | 0.10 | $\pm 0.05$ | - |
| A2 | 0.86 | 0.86 | $\pm 0.09$ | - |
| b | 0.33 | 0.23 | $+0.07 /-0.08$ | - |
| c | 0.18 | 0.18 | $\pm 0.05$ | - |
| D | 3.00 | 3.00 | $\pm 0.10$ | 1,3 |
| E | 4.90 | 4.90 | $\pm 0.15$ | - |
| E1 | 3.00 | 3.00 | $\pm 0.10$ | 2,3 |
| e | 0.65 | 0.50 | Basic | - |
| L | 0.55 | 0.55 | $\pm 0.15$ | - |
| L1 | 0.95 | 0.95 | Basic | - |
| N | 8 | 10 | Reference | - |

Rev. D 2/07
NOTES:

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.
3. Dimensions " D " and " $E 1$ " are measured at Datum Plane " H ".
4. Dimensioning and tolerancing per ASME Y14.5M-1994.

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